

FLEXIBLE HYBRID ELECTRONICS INDUSTRY DAY

12-08-15

AGENDA

- 8:00- 8:30 **Check in**
- 8:30-8:55 **Overview of the FlexTech Team and FHEMII**
Paul Semenza, Director of Commercialization, FlexTech
- 8:55-9:20 **AU Harsh Environment Node**
Pradeep Lall, Ph.D., Endowed Professor, Auburn University
- 9:20-9:45 **Flexible Electronics Applications in Aerospace Environments**
Benjamin Leevers, Govt CTO NextFlex, Air Force Research Laboratories
- 9:45 – 10:10 **Challenges and opportunities in the flexible electronics manufacturing**
Amanda Schrand, Additive Manufacturing for Fuze Electronics and Design Fuzes, Eglin AFB
- 10:10-10:35 **Importance of Flexible Electronics in Army Applications**
Mike Bieri, AMRDEC
- 10:35-10:45 **Break**
- 10:45-11:10 **Flexible Electronics – A Parts and Packaging Perspective**
Bruce Hughes and David Locker, AMRDEC
- 11:10-11:35 **Flexible Electronics in Commercial and Military Application**
Erick Seltmann, Boeing
- 11:35-12:00 **Survivability Testing of Flexible Electronics – Pop Shock**
Ryan Lowe, ARA Associates
- 12:00-1:15 **Working Lunch – Importance of Manufacturing to the Alabama Economy**
John M. Mason, Jr., Vice President for Research and Economic Development, Auburn University
Christopher B. Roberts, Dean, Samuel Ginn College of Engineering, Auburn University
- 1:15-1:40 **LM priorities and Objectives for FHEMII**
Jeff Stuart and Jim Libous, Lockheed Martin
- 1:40-2:05 **Additive Manufacturing of Flexible Electronics**
Mike O'Reilly, Director, Optomec, Inc.
- 2:05-2:30 **Ultra-thin Chips for Flexible Electronics**
Val Marinov, Uniqarta, Inc.
- 2:30-2:55 **Inkjet and Aerosol Jet for Digital Deposition**
Tim Luong, Ceradrop MGI
- 2:55-3:05 **Break**
- 3:05-5:00 **Break-Out Sessions**
This section of the program will be a working session on project road-mapping, teaming and proposal development for the 1st year.